

ON Semiconductor®

FDD3672-F085

N-Channel UltraFET Trench MOSFET

100V, **44A**, **28m** Ω

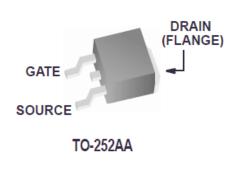
Features

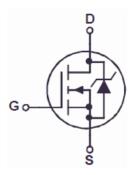
- Typ $r_{DS(on)} = 24m\Omega$ at $V_{GS} = 10V$, $I_D = 44A$
- Typ $Q_{g(10)} = 24nC$ at $V_{GS} = 10V$
- Low Miller Charge
- Low Q_{rr} Body Diode
- Optimized efficiency at high frequencies
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

Applications

- DC/DC converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Switch for 24V and 48V Systems
- High Voltage Synchronous Rectifier







Units

Max

MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	100	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (T _C < 30°C, V _{GS} = 10V)	44	Α
'D	Pulsed	See Figure 4	A
E _{AS}	Single Pulse Avalanche Energy (Note	1) 73	mJ
D	Power Dissipation	144	W
P_D	Derate above 25°C	0.96	W/°C
T _J , T _{STG}	Operating and Storage Temperature	-55 to +175	οС

Thermal Characteristics

$R_{\theta JC}$	Maximum Thermal Resistance Junction to Case	1.04	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance Junction to Ambient TO-263,1in ² copper pad area	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD3672	FDD3672-F085	TO-252AA	330mm	16mm	2500 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Parameter

Off Characteristics								
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V		
	Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1	μА		
DSS	Zero Gate Voltage Drain Current	$T_{J} = 150^{\circ}C$	-	-	250	μΑ		
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA		

Test Conditions

Min

Тур

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2	3	4	V
		I _D = 44A, V _{GS} = 10V	-	0.024	0.028	Ω
r _{DS(on)}	Drain to Source On Resistance	$I_D = 21A, V_{GS} = 6V,$	-	0.028	0.047	Ω
		$I_D = 44A$, $V_{GS} = 10V$, $T_J = 175$ °C	-	0.063	0.074	Ω

Dynamic Characteristics

C _{iss}	Input Capacitance	V 05V V	0) /	-	1635	-	рF
Coss	Output Capacitance	$V_{DS} = 25V, V_{GS} = 0$ $f = 1MHz$	UV,	-	240	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/12		-	60	-	pF
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V		-	24	36	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0$ to $2V$	V _{DD} = 50V	-	3	4.5	nC
Q _{gs}	Gate to Source Gate Charge		$I_{D} = 44A$	-	8.3	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		$I_g = 1.0 \text{mA}$	-	5.3	-	nC
Q _{gd}	Gate to Drain "Miller" Charge			-	5.8	-	nC

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Switch	ing Characteristics						

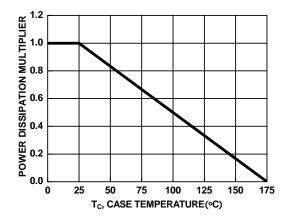
t _{on}	Turn-On Time		-	-	78	ns
t _{d(on)}	Turn-On Delay Time		-	12	-	ns
t _r	Turn-On Rise Time	$V_{DD} = 50V, I_D = 44A,$	-	37	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 11\Omega$	-	24	-	ns
t _f	Turn-Off Fall Time		-	44	-	ns
t _{off}	Turn-Off Time		-	-	70	ns

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Voltage	Source to Drain Diode Voltage	I _{SD} = 44A	-	0.9	1.25	V
	I _{SD} = 21A		0.8	1.0	V	
t _{rr}	Reverse Recovery Time	$I_{F} = 44A, dI_{SD}/dt = 100A/\mu s$	-	44	57	ns
Q _{rr}	Reverse Recovery Charge		-	58	76	nC

1: Starting $T_J = 25^{\circ}C$, L = 0.2mH, $I_{AS} = 27A$

Typical Characteristics



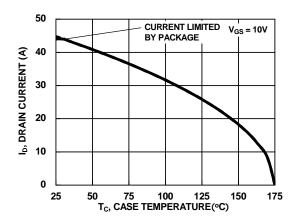
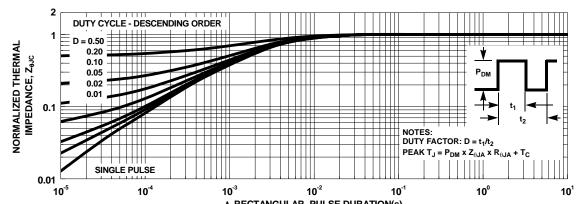


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

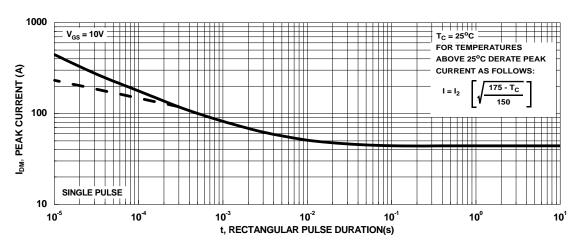


Figure 4. Peak Current Capability

Typical Characteristics

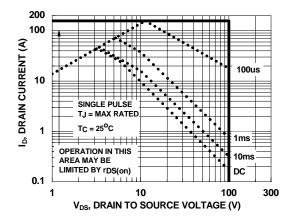


Figure 5. Forward Bias Safe Operating Area

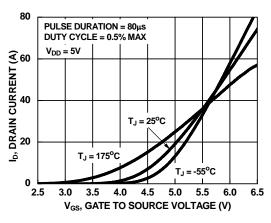


Figure 7. Transfer Characteristics

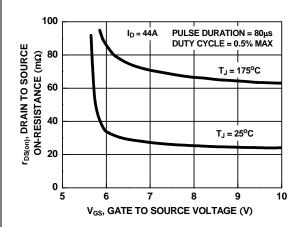
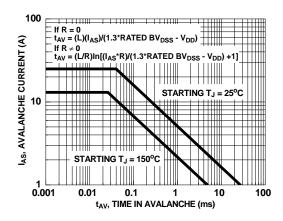


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

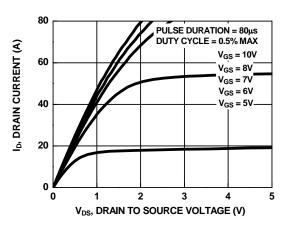


Figure 8. Saturation Characteristics

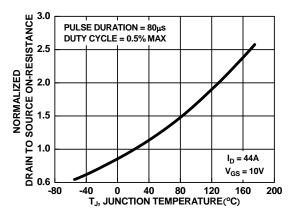


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

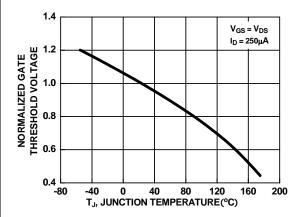


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

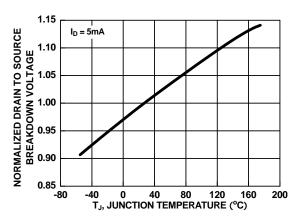


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

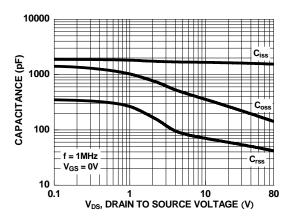


Figure 13. Capacitance vs Drain to Source Voltage

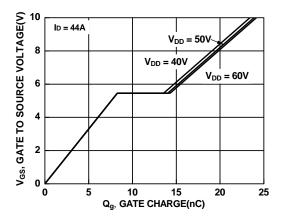


Figure 14. Gate Charge vs Gate to Source Voltage

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